

ASICS I



- news
 - 3 working bump bonded (asic+sensor) agipd02 systems
 - agip03 wire bonded (without sensor)
- discussed yesterday further testing
 - AGIPD01: irradiation test (10 and 100 MGy) without sensor
3 weeks
 - AGIPD02: uniformity (noise, gain, offsets), noise in different gain stages, noise for different preamps (2x current, protection diode), n-fet switch in storage cell
2 months
 - AGIPD03 (also hpad03): test rad hard storage cells
new command based serial interface
1 month

Difficult to say

ASICS II



- discussed yesterday XDAC comments and questions (Ulrich will send email around)
- would like to submit variations of off-chip driver and test it with prototype readout system, possibly also add other blocks (further iteration of serial interface if needed)

Dominic Greiffenberg started mid November